PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT3511896

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
SARAVJEET SINGH	07/15/2011
BRAD EATON	07/20/2011
AJAY KUMAR	07/15/2011
WEI-SHENG LEI	07/15/2011
JAMES M. HOLDEN	08/10/2011
MADHAVA RAO YALAMANCHILI	07/15/2011
TODD J. EGAN	07/15/2011

RECEIVING PARTY DATA

Name:	Applied Materials, Inc.
Street Address:	3050 Bowers Avenue
City:	Santa Clara
State/Country:	CALIFORNIA
Postal Code:	95054

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	14166715

CORRESPONDENCE DATA

Fax Number: (503)439-6073

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: (503) 439-8778
Email: gigi_hoover@bstz.com
Correspondent Name: JUSTIN K. BRASK
Address Line 1: 1279 OAKMEAD PARKWAY
Address Line 4: SUNNYVALE, CALIFORNIA 94085-4040

ATTORNEY DOCKET NUMBER:	4887.P1030D
NAME OF SUBMITTER:	JUSTIN K. BRASK
SIGNATURE:	/Justin K. Brask/
DATE SIGNED:	09/03/2015

Total Attachments: 6
source=4887P1030D_Assignment_090315#page1.tif
source=4887P1030D_Assignment_090315#page2.tif
source=4887P1030D_Assignment_090315#page3.tif
source=4887P1030D_Assignment_090315#page4.tif
source=4887P1030D_Assignment_090315#page5.tif
source=4887P1030D_Assignment_090315#page6.tif

Case # 016421/ETCH/MASK-ETCH/MDD

ASSIGNMENT FOR APPLICATION FOR PATENT

WHEREAS:

Names and Addresses of Inventors:

1)	Saravjeet Singh 1000 Kiely Blvd #74 Santa Clara, CA 95051	2)	Brad Eaton 563 8th Avenue Menlo Park, CA 94025
3)	Ajay Kumar 10457 Manzanita Court Cupertino, CA 95014	4)	Wei-Sheng Lei 1786 Duvall Drive San Jose, CA 95130
5)	James M. Holden 5088 Golden Drive San Jose, CA 95129	6)	Madhava Rao Yalamanchili 1660 Avenida de Los Padres Morgan Hill, CA 95037
7)	Todd J. Egan 145 Hillview Drive Fremont, CA 94536		

(hereinafter referred to as Assignors), have invented a certain invention entitled:

HYBRID LASER AND PLASMA ETCH WAFER DICING USING SUBSTRATE CARRIER

for which application for Letters Patent in the United States was filed on June 15, 2011, under Serial No. 13/161,052, executed on even date herewith; and

WHEREAS, Applied Materials, Inc., a corporation of the State of Delaware, having a place of business at 3050 Bowers Avenue, Santa Clara, California 95054 (hereinafter referred to as Assignee), is desirous of acquiring the entire right, title and interest in and to said application (hereinafter referred to as the Application), and the invention disclosed therein (hereinafter referred to as the Invention), and in and to all embodiments of the Invention, heretofore conceived, made or discovered by said Assignors, and in and to any and all patents, inventor's certificates and other forms of protection (hereinafter referred to as the Patents) thereon granted in any and all countries and groups of countries.

NOW, THEREFORE, in consideration of good and valuable consideration acknowledged by said Assignors to have been received in full from said Assignee:

1. Said Assignors hereby sell, assign, transfer and convey to Assignee the full and exclusive right, title and interest (a) in and to said Application and said Invention; (b) in and to all rights to apply for patents on said Invention in any and all countries pursuant to the International Convention for the Protection of Industrial Property or otherwise; (c) in and to any and all Applications filed and any and all Patents granted on said Invention in any and all countries and groups of countries, including each and every Application filed and each and every Patent granted on any application which is a division, substitution, or continuation of said Application; and (d) in and to each and every reissue or extension of any of said Patents.

2. Said Assignors hereby covenant and agree to cooperate with said Assignee to enable said Assignee to enjoy to the fullest extent the right, title and interest to said Invention herein conveyed in any and all countries and groups of countries. Such cooperation by said Assignors shall include prompt production of pertinent facts and documents, giving testimony, execution of petitions, oaths, specifications, declarations or other papers, and other assistance all to the extent deemed necessary or desirable by said Assignee (a) for perfecting in said Assignee the right, title and interest herein conveyed; (b) for

prosecuting any of said applications; (c) for filing and prosecuting substitute, divisional, continuing or additional applications covering said Invention; (d) for filing and prosecuting applications for reissuance of any of said Patents; (e) for interference or other priority proceedings involving said Invention; and (f) for legal proceedings involving said Invention and any application therefor and any Patents granted thereon, including without limitation opposition proceedings, cancellation proceedings, priority contests, public use proceedings, infringement actions and court actions; provided, however, that the expense incurred by said Assignors in providing such cooperation shall be paid for by said Assignee.

3. The term and covenants of this agreement shall inure to the benefit of said Assignee, its successors, assigns and other legal representatives, and shall be binding upon said Assignors, their respective heirs, legal representatives and assigns.

4. Said Assignors hereby warrant and represent that they have not entered and will not enter into any assignment, contract, or understanding in conflict herewith.

IN WITNESS WHEREOF, the said Assignors have executed and delivered this instrument to said Assignee on the dates indicated below.

1) 07/15/11
Date Saravjeet Singh

2) 7/20/2011
Date Brad Eaton

3) 07/15/11
Date Ajay Kumar

4) 7-15-2011
Date Wei-Sheng Lei

5)
Date James M. Holden

6) 7-15-2011 Rao Yalamanchili
Date Madhava Rao Yalamanchili

7)
Date Todd J. Egan

Case # 016421/ETCH/MASK-ETCH/MDD

ASSIGNMENT FOR APPLICATION FOR PATENT

WHEREAS:

Names and Addresses of Inventors:

1)	Saravjeet Singh 1000 Kiely Blvd #74 Santa Clara, CA 95051	2)	Brad Eaton 563 8th Avenue Menlo Park, CA 94025
3)	Ajay Kumar 10457 Manzanita Court Cupertino, CA 95014	4)	Wei-Sheng Lei 1786 Duvall Drive San Jose, CA 95130
5)	James M. Holden 5088 Golden Drive San Jose, CA 95129	6)	Madhava Rao Yalamanchili 1660 Avenida de Los Padres Morgan Hill, CA 95037
7)	Todd J. Egan 145 Hillview Drive Fremont, CA 94536		

(hereinafter referred to as Assignors), have invented a certain invention entitled:

HYBRID LASER AND PLASMA ETCH WAFER DICING USING SUBSTRATE CARRIER

for which application for Letters Patent in the United States was filed on June 15, 2011, under Serial No. 13/161,052, executed on even date herewith; and

WHEREAS, Applied Materials, Inc., a corporation of the State of Delaware, having a place of business at 3050 Bowers Avenue, Santa Clara, California 95054 (hereinafter referred to as Assignee), is desirous of acquiring the entire right, title and interest in and to said application (hereinafter referred to as the Application), and the invention disclosed therein (hereinafter referred to as the Invention), and in and to all embodiments of the Invention, heretofore conceived, made or discovered by said Assignors, and in and to any and all patents, inventor's certificates and other forms of protection (hereinafter referred to as the Patents) thereon granted in any and all countries and groups of countries.

NOW, THEREFORE, in consideration of good and valuable consideration acknowledged by said Assignors to have been received in full from said Assignee:

1. Said Assignors hereby sell, assign, transfer and convey to Assignee the full and exclusive right, title and interest (a) in and to said Application and said Invention; (b) in and to all rights to apply for patents on said Invention in any and all countries pursuant to the International Convention for the Protection of Industrial Property or otherwise; (c) in and to any and all Applications filed and any and all Patents granted on said Invention in any and all countries and groups of countries, including each and every Application filed and each and every Patent granted on any application which is a division, substitution, or continuation of said Application; and (d) in and to each and every reissue or extension of any of said Patents.

2. Said Assignors hereby covenant and agree to cooperate with said Assignee to enable said Assignee to enjoy to the fullest extent the right, title and interest to said Invention herein conveyed in any and all countries and groups of countries. Such cooperation by said Assignors shall include prompt production of pertinent facts and documents, giving testimony, execution of petitions, oaths, specifications, declarations or other papers, and other assistance all to the extent deemed necessary or desirable by said Assignee (a) for perfecting in said Assignee the right, title and interest herein conveyed;

(b) for prosecuting any of said applications; (c) for filing and prosecuting substitute, divisional, continuing or additional applications covering said Invention; (d) for filing and prosecuting applications for reissuance of any of said Patents; (e) for interference or other priority proceedings involving said Invention; and (f) for legal proceedings involving said Invention and any application therefor and any Patents granted thereon, including without limitation opposition proceedings, cancellation proceedings, priority contests, public use proceedings, infringement actions and court actions; provided, however, that the expense incurred by said Assignors in providing such cooperation shall be paid for by said Assignee.

3. The term and covenants of this agreement shall inure to the benefit of said Assignee, its successors, assigns and other legal representatives, and shall be binding upon said Assignors, their respective heirs, legal representatives and assigns.

4. Said Assignors hereby warrant and represent that they have not entered and will not enter into any assignment, contract, or understanding in conflict herewith.

IN WITNESS WHEREOF, the said Assignors have executed and delivered this instrument to said Assignee on the dates indicated below.

1) ____________________ ________________________________
Date Saravjeet Singh

2) ____________________ ________________________________
Date Brad Eaton

3) ____________________ ________________________________
Date Ajay Kumar

4) ____________________ ________________________________
Date Wei-Sheng Lei

5) August 10, 2011 James M Holden
Date James M. Holden

6) ____________________ ________________________________
Date Madhava Rao Yalamanchili

7) ____________________ ________________________________
Date Todd J. Egan

Case # 016421/ETCH/MASK-ETCH/MDD

ASSIGNMENT FOR APPLICATION FOR PATENT

WHEREAS:

Names and Addresses of Inventors:

1)	Saravjeet Singh 1000 Kiely Blvd #74 Santa Clara, CA 95051	2)	Brad Eaton 563 8th Avenue Menlo Park, CA 94025
3)	Ajay Kumar 10457 Manzanita Court Cupertino, CA 95014	4)	Wei-Sheng Lei 1786 Duvall Drive San Jose, CA 95130
5)	James M. Holden 5088 Golden Drive San Jose, CA 95129	6)	Madhava Rao Yalamanchili 1660 Avenida de Los Padres Morgan Hill, CA 95037
7)	Todd J. Egan 145 Hillview Drive Fremont, CA 94536		

(hereinafter referred to as Assignors), have invented a certain invention entitled:

HYBRID LASER AND PLASMA ETCH WAFER DICING USING SUBSTRATE CARRIER

for which application for Letters Patent in the United States was filed on June 15, 2011, under Serial No. 13/161,052, executed on even date herewith; and

WHEREAS, Applied Materials, Inc., a corporation of the State of Delaware, having a place of business at 3050 Bowers Avenue, Santa Clara, California 95054 (hereinafter referred to as Assignee), is desirous of acquiring the entire right, title and interest in and to said application (hereinafter referred to as the Application), and the invention disclosed therein (hereinafter referred to as the Invention), and in and to all embodiments of the Invention, heretofore conceived, made or discovered by said Assignors, and in and to any and all patents, inventor's certificates and other forms of protection (hereinafter referred to as the Patents) thereon granted in any and all countries and groups of countries.

NOW, THEREFORE, in consideration of good and valuable consideration acknowledged by said Assignors to have been received in full from said Assignee:

1. Said Assignors hereby sell, assign, transfer and convey to Assignee the full and exclusive right, title and interest (a) in and to said Application and said Invention; (b) in and to all rights to apply for patents on said Invention in any and all countries pursuant to the International Convention for the Protection of Industrial Property or otherwise; (c) in and to any and all Applications filed and any and all Patents granted on said Invention in any and all countries and groups of countries, including each and every Application filed and each and every Patent granted on any application which is a division, substitution, or continuation of said Application; and (d) in and to each and every reissue or extension of any of said Patents.

2. Said Assignors hereby covenant and agree to cooperate with said Assignee to enable said Assignee to enjoy to the fullest extent the right, title and interest to said Invention herein conveyed in any and all countries and groups of countries. Such cooperation by said Assignors shall include prompt production of pertinent facts and documents, giving testimony, execution of petitions, oaths, specifications, declarations or other papers, and other assistance all to the extent deemed necessary or desirable by said Assignee (a) for perfecting in said Assignee the right, title and interest herein conveyed;

(b) for prosecuting any of said applications; (c) for filing and prosecuting substitute, divisional, continuing or additional applications covering said Invention; (d) for filing and prosecuting applications for reissuance of any of said Patents; (e) for interference or other priority proceedings involving said Invention; and (f) for legal proceedings involving said Invention and any application therefor and any Patents granted thereon, including without limitation opposition proceedings, cancellation proceedings, priority contests, public use proceedings, infringement actions and court actions; provided, however, that the expense incurred by said Assignors in providing such cooperation shall be paid for by said Assignee.

3. The term and covenants of this agreement shall inure to the benefit of said Assignee, its successors, assigns and other legal representatives, and shall be binding upon said Assignors, their respective heirs, legal representatives and assigns.

4. Said Assignors hereby warrant and represent that they have not entered and will not enter into any assignment, contract, or understanding in conflict herewith.

IN WITNESS WHEREOF, the said Assignors have executed and delivered this instrument to said Assignee on the dates indicated below.

1) ______________________ ______________________________
Date Saravjeet Singh

2) ______________________ ______________________________
Date Brad Eaton

3) ______________________ ______________________________
Date Ajay Kumar

4) ______________________ ______________________________
Date Wei-Sheng Lei

5) ______________________ ______________________________
Date James M. Holden

6) ______________________ ______________________________
Date Madhava Rao Yalamanchili

7) 07/15/11 ______________________________
Date Todd J. Egan